

<1995 ()>

1995

()

95 109 .(8~10)
460 , 27 1017 530 ,
620 1637 .

1.

가.

•	• 1 105 • - - , 가 (: 10)
•	• 2 4
•	• , , .

.

16

•
• 2/3

2.

가. :

• :
• : 8%
• : 3 5
• : 100%

	A1	- 가 - , 가 (7xxx) - ,
		- 30μm 가 - Audio Cable, Magnetic Wire, Bonding Wire
	PDP	- - Cell Design - , - (full color)
	FED Panel	- - Field Emitter Array , -
	Multi-Color EL Panel	- - Panel
	Oscillator & Filter	- SMD Type TCXO - SMD Type Filter
	Module	- , , , , 가 - - - - 가
	Chip Inductor	- - Chip Inductor
	Multi Chip Module	- , , Via Hole -
		- - -
		- High Modulus Low Shrinkage, High Tenacity (Tire-Cord , ,)
	가가	- - , -
	~ Line	- Cone - Cone - Cone - - Auto Packing
/ 가		- (, Silk) (-80 , 1) - PET () - Microwave (Roll Batch System) - (= 1 : 4, = 1 : 10)
	가	- Cool Touch - -
	가	- Assort - Cutting System - Pattern -
		- -

/	•	- 2 CAD/CAM
	• Line	- Modular Cell
	• 가	- Y-ZIP
	• , 가	-
	•	- (, , , Pilot Plant /)
	• Software	- Parameter - DB - (, 가) DB
	•	- HDPE, LDPE - PET - EPS PS
	• 가 (Microlithography)	- 0.3 ~ 0.2 - (X ,)
	•	- (100 / 1) - ()
	•	- , , , , - Recycle 가
Chemicals	•	- HFC-134a - ISO VG68, 100 Polyolester - : 0.1% , TAN : 0.05
	•	- 200 (UL : N S)
	• /	- 가
	•	-
	•	- , .
	•	- HIV, HCV, 3 - HIV
	• ,	- 가
	• , CHIP	- Tape Casting, Extruding, Printing Sheet - Pattern(X, Y, Z via Hole Filling) - Paste Matching - Package
	•	- , - 가 ,
	•	- , , Engineering
	• 가	- 20~50t/ - 가 가 - 2 Air Injection